

AMENDMENTS TO THE CLAIMS:

Please cancel claims 7-10 and 21-24, without prejudice or disclaimer of their subject matter, and amend claim 1 as indicated below. This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A polishing slurry for CMP of Cu, which comprises:
a first complexing agent containing quinaldinic acid; [[and]]
a second complexing agent containing quinolinic acid;
an oxidizing agent selected from the group consisting of persulfuric acid, ammonium persulfate and hydrogen peroxide;
a polishing rate promoting agent selected from the group consisting of glycine and alanine;
polishing particles containing colloidal silica; and
a surfactant containing potassium dodecylbenzenesulfonate and acetylene diol-based nonion.

2. (Original) The polishing slurry for CMP of Cu according to claim 1, wherein a mixing ratio of said first complexing agent to said second complexing agent is within the range of 2:8 to 8:2 based on weight.

3. (Original) The polishing slurry for CMP of Cu according to claim 1, wherein a mixing ratio of said first complexing agent to said second complexing agent is within the range of 4:6 to 6:4 based on weight.

4-24. (Canceled)